IC Taiwan Grand Challenge 第三梯次獲獎名單

團隊名稱	產品名稱	國別
3D Architech, Inc.	Metal manufacturing for energy efficiency improvement	UNITED STATES
AlixLabs AB	Atomic Layer Pitch Splitting: a breakthrough equipment solution for advanced semiconductor manufacturing	SWEDEN
Brilliant Silicon Technology Co., Ltd.	RF Chipset for Low Earth Orbit (LEO) user terminal	TAIWAN
DeepMentor Inc.	CNN AI IP-DeepLogCore & LLM AI IP-DeepTransformCore & AI Tools-DeepExpert	TAIWAN
EndoSemio Co., Ltd.	NBI Fusion AI-Powered ENT Endoscope: Next-Gen Nasopharyngeal Cancer Early Detection	TAIWAN
femtoAI	Sparse Processing Unit 001 (SPU-001)	UNITED STATES
HyperAccel	Bertha-Edge (BerthaE)	REPUBLIC OF KOREA
PurCity ApS	GapS panels	DENMARK

順序依照團隊名稱字母排列